

Proven Materials for Reliable Servers

PCBA Materials

Main Board

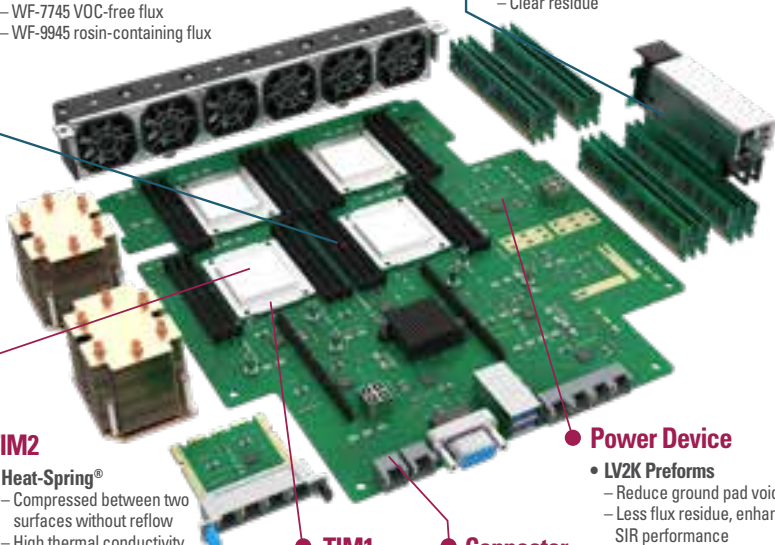
- **Indium10.8HF Solder Paste**
 - Eliminates HIP and NWO when BGAs warp
 - Excellent wetting on different surface
- **Indium10.2HFA Solder Paste**
 - Non-tacky residue with excellent ICT performance
 - Excellent HIP and NWO performance
 - Excellent conformal coating compatibility
- **Durafuse® LT Low-Temperature Alloy**
 - More than two orders of magnitude better than Bi-containing low-temperature materials
 - TCT performance can be better than SAC305
- **Solder Fortification® Preforms**
 - Added solder volume to improve mechanical reliability
- **Wave Fluxes**
 - WF-7745 VOC-free flux
 - WF-9945 rosin-containing flux

Memory Module

- **Indium8.9HF Solder Paste**
 - Restricted flux residue
 - Excellent transfer efficiency
- **Durafuse® LT Low-Temperature Alloy**
 - Improving drop shock resistance
 - Improving TCT performance
- **Indium5.7LT-1 Solder Paste**
 - Low-temperature
 - Clear residue

Graphic Card

- **Indium10.8HF Solder Paste**
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 - Excellent wetting on different surfaces
- **Indium5.7LT-1 Solder Paste**
 - Low-temperature
 - Clear residue



TIM2

- **Heat-Spring®**
 - Compressed between two surfaces without reflow
 - High thermal conductivity
 - Excellent thermal cycling performance

TIM1

- Solder TIM
- Liquid Metal
- Phase Change Metal Alloys

Connector

- **Solder Fortification® Preforms**
 - Added solder volume to improve mechanical reliability

Power Device

- **LV2K Preforms**
 - Reduce ground pad voiding
 - Less flux residue, enhance SIR performance

Engineered Solders



Contact our engineers: askus@indium.com

Learn more: www.indium.com

From One Engineer To Another®

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

